

ROTOTYPE S.p.A.

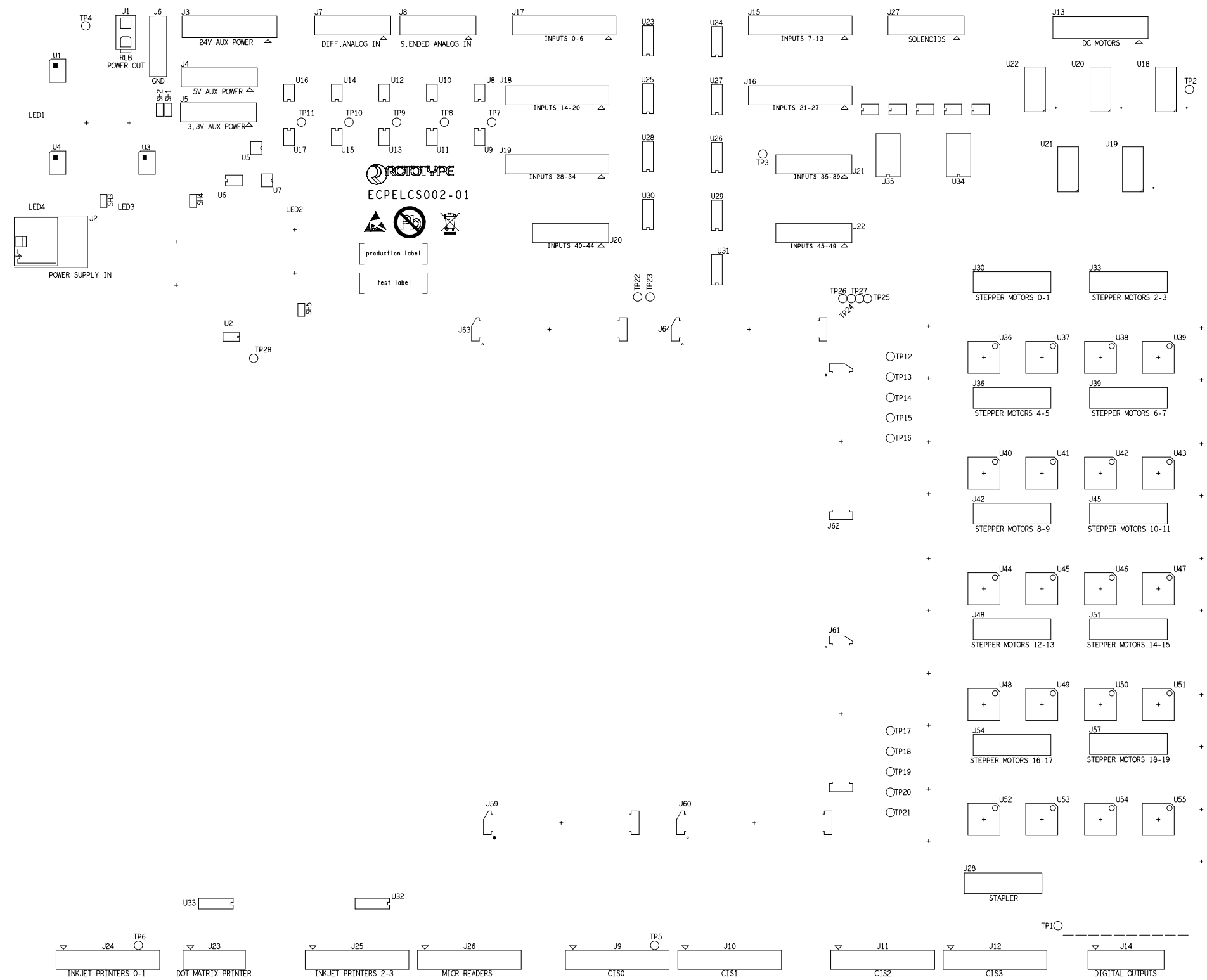
Board: RPB Rev.1

PCB: ECPCLCS002 File: ECPCLCS002-01.BRD

ASSEMBLAGGIO LC

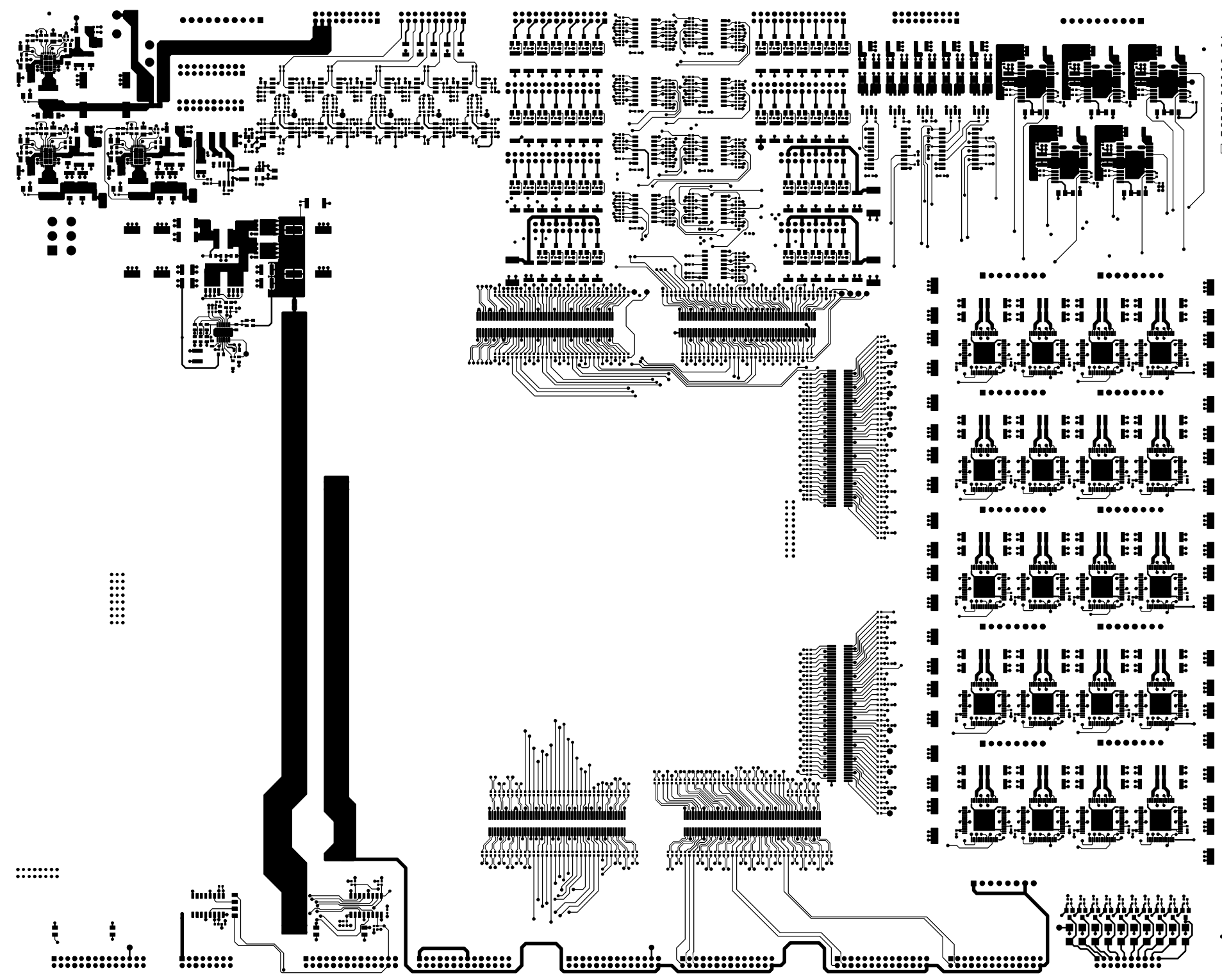
Data:12/11/2020 DESIGN:PCBDes CHECK:AG Pag:01/12

&gt;&gt; STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO &lt;&lt;



ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
SERIGRAFIA LC			
ESEGUIRE IL CLEAN-UP RIFERITO AL SOLDER-RESIST LC			
Data:12/11/2020		DESIGN:PCBDes	CHECK:AG
			Page:02/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

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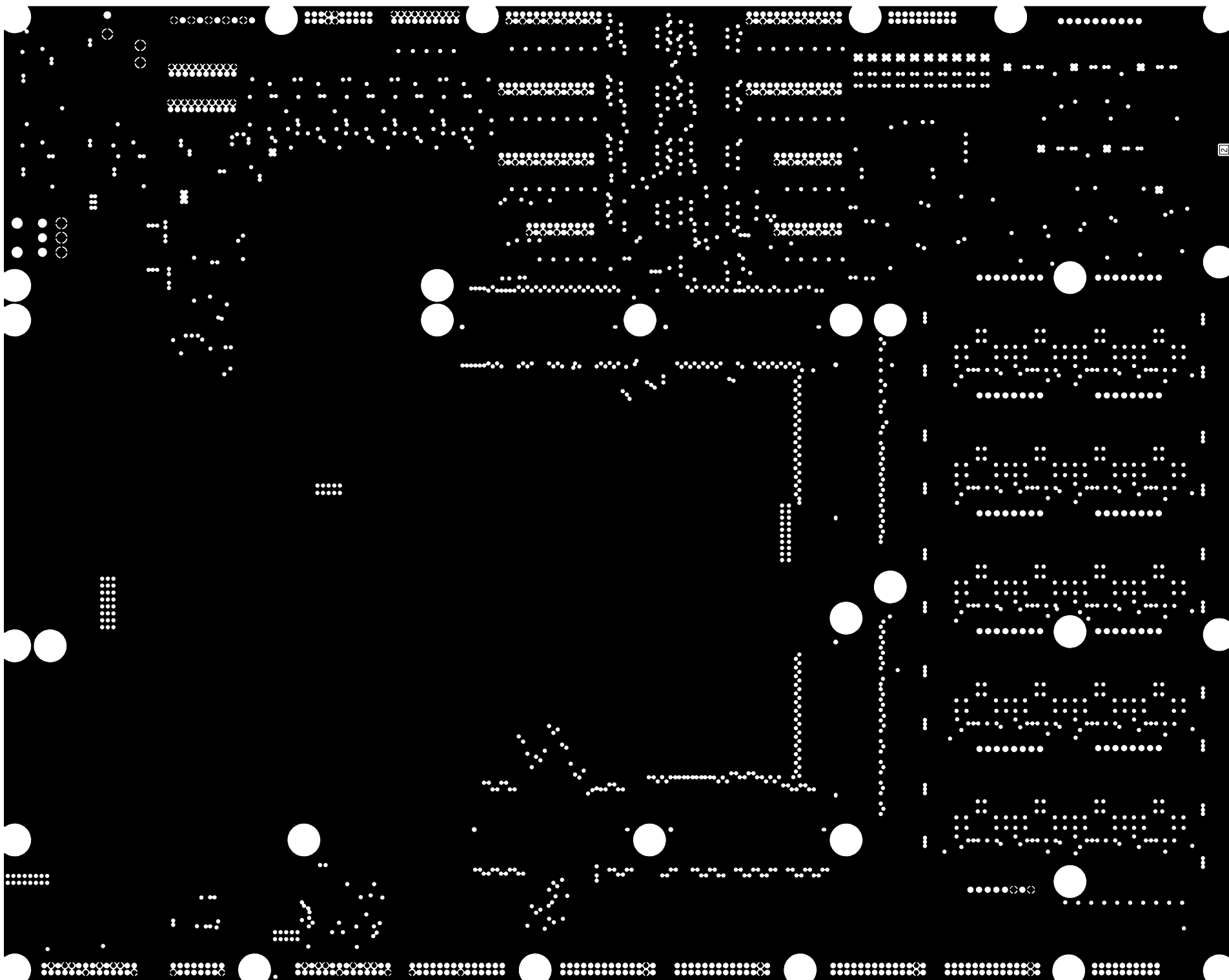


ECPELCS002-01

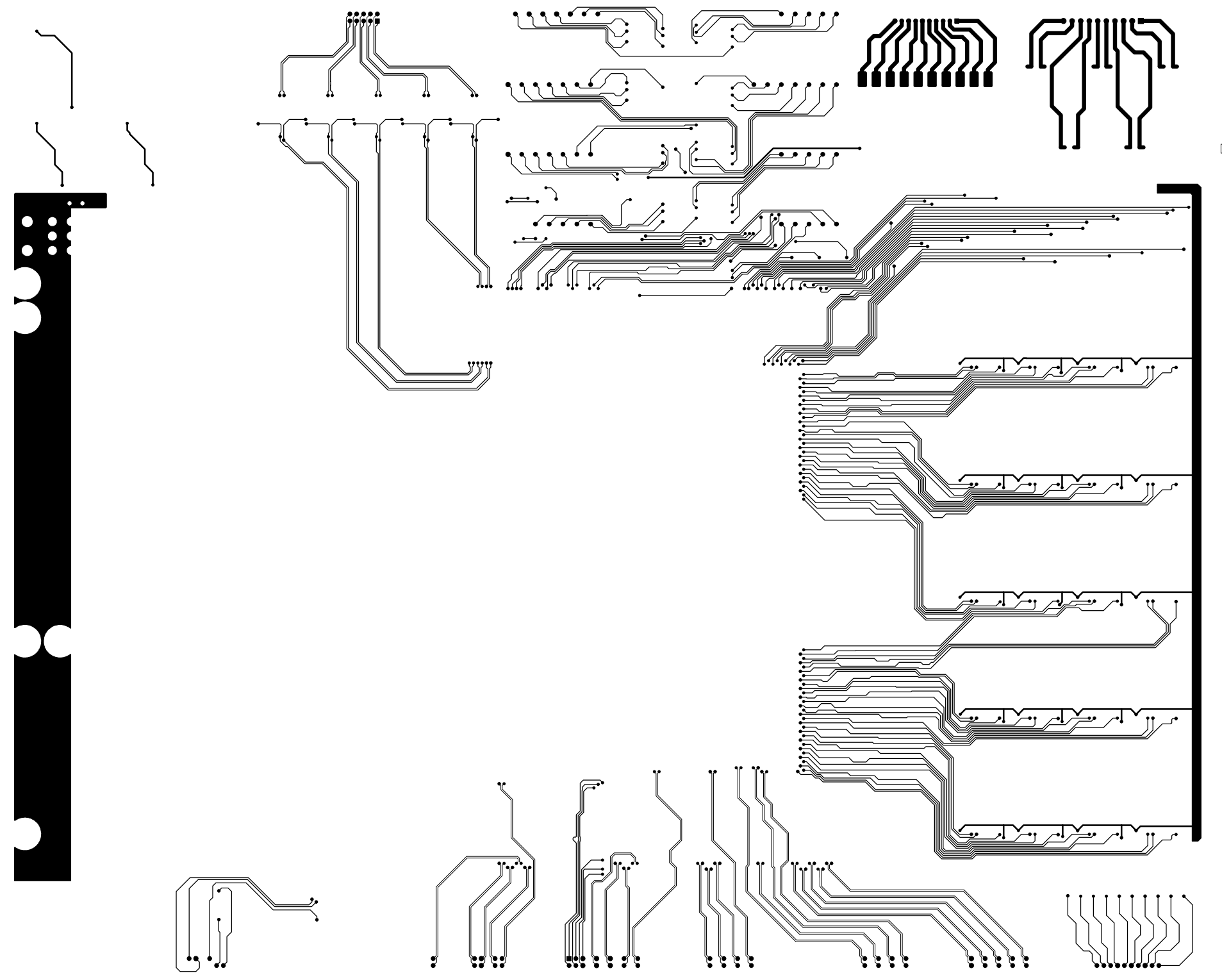


ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
LAYER 1			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:03/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

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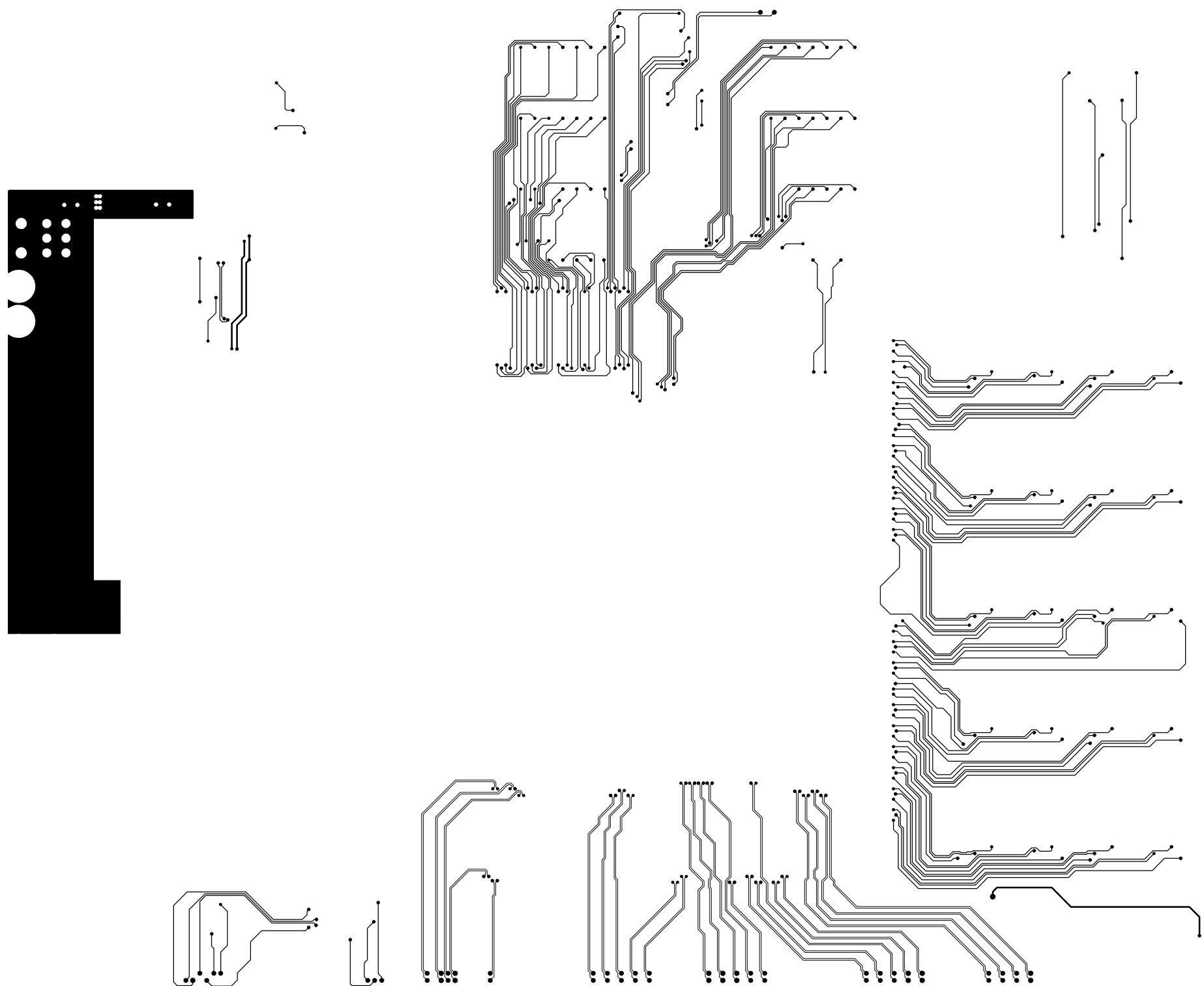


ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
LAYER 2			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:04/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

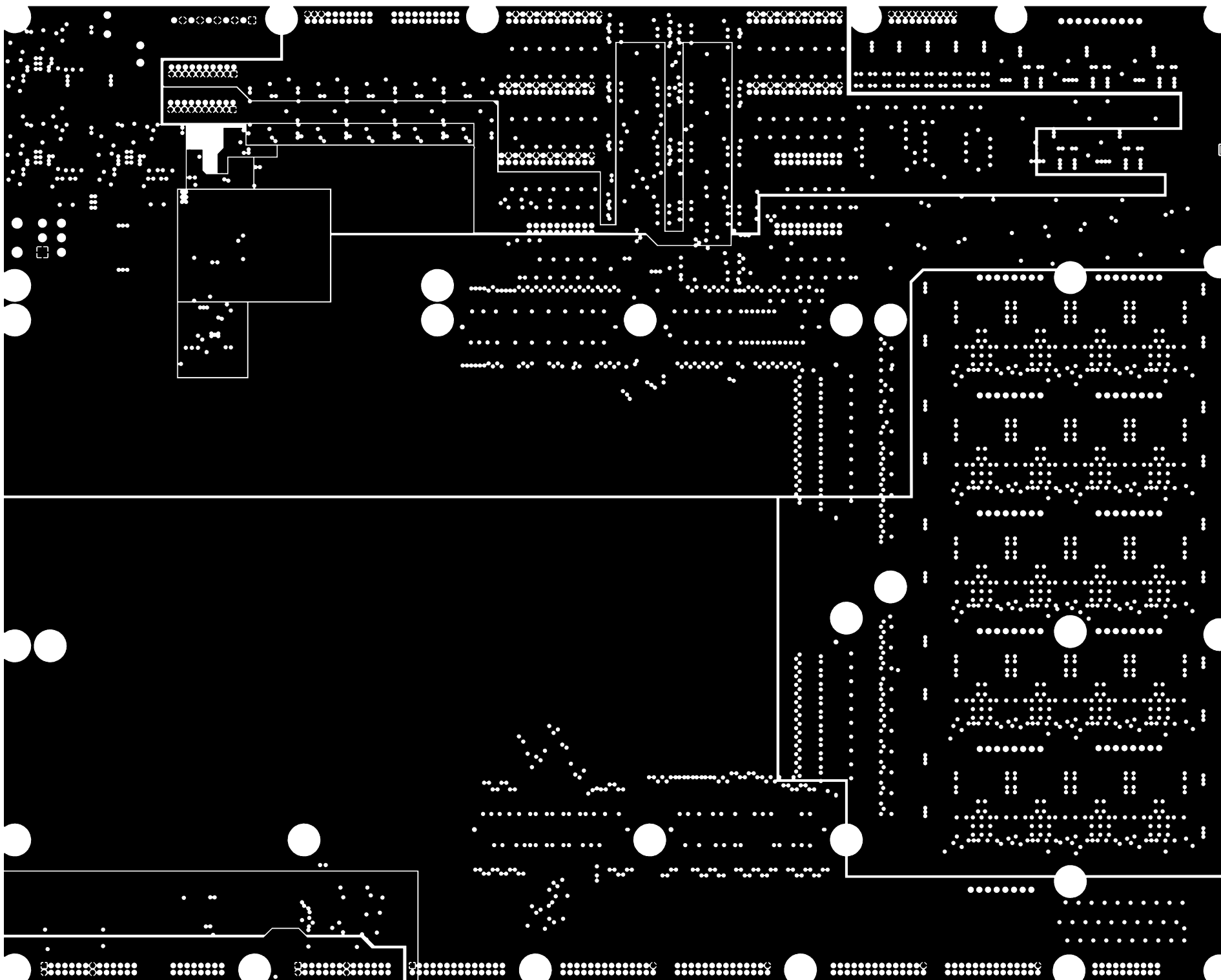


ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
LAYER 3			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:05/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

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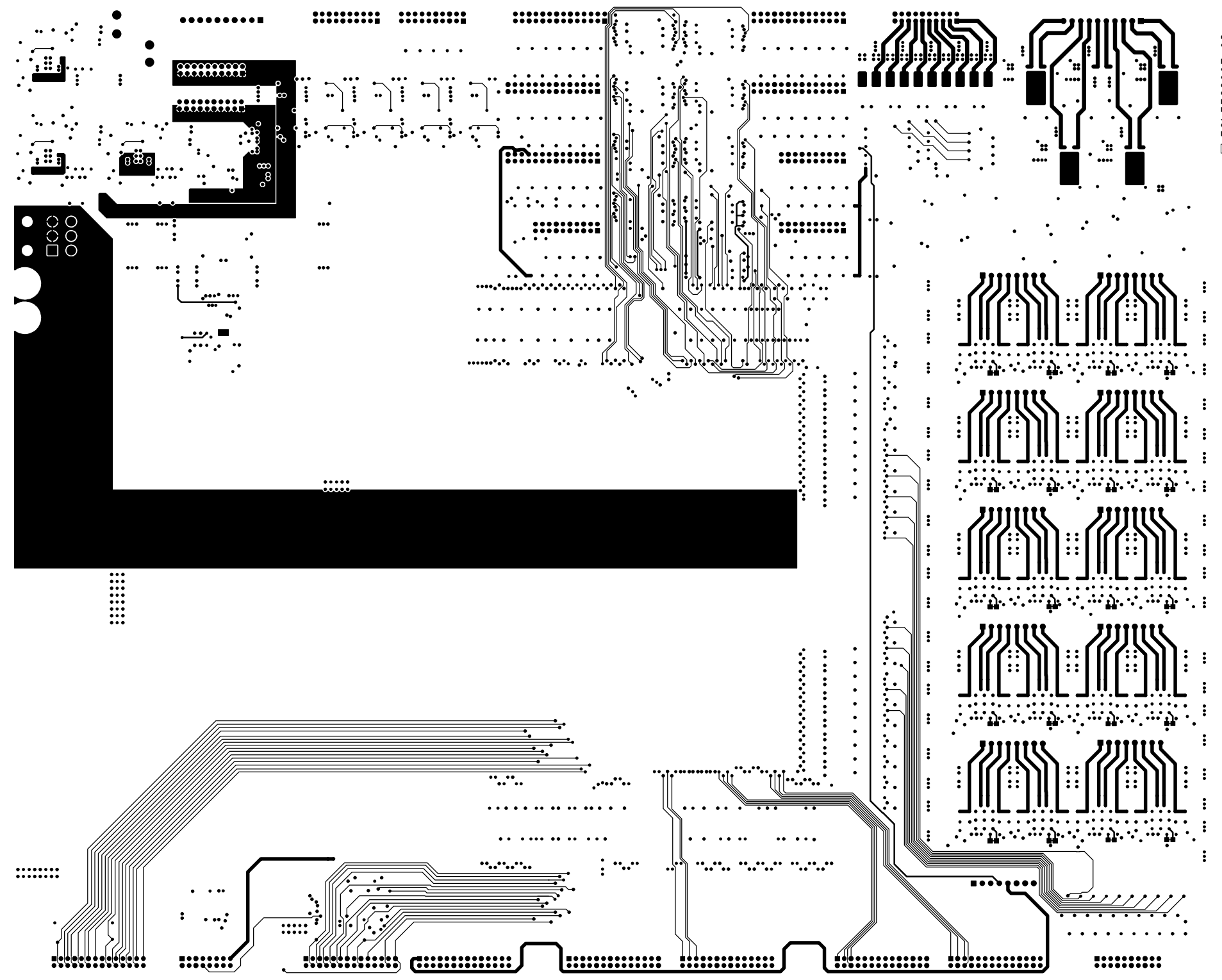


ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
LAYER 4			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:06/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			



ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
LAYER 5			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:07/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

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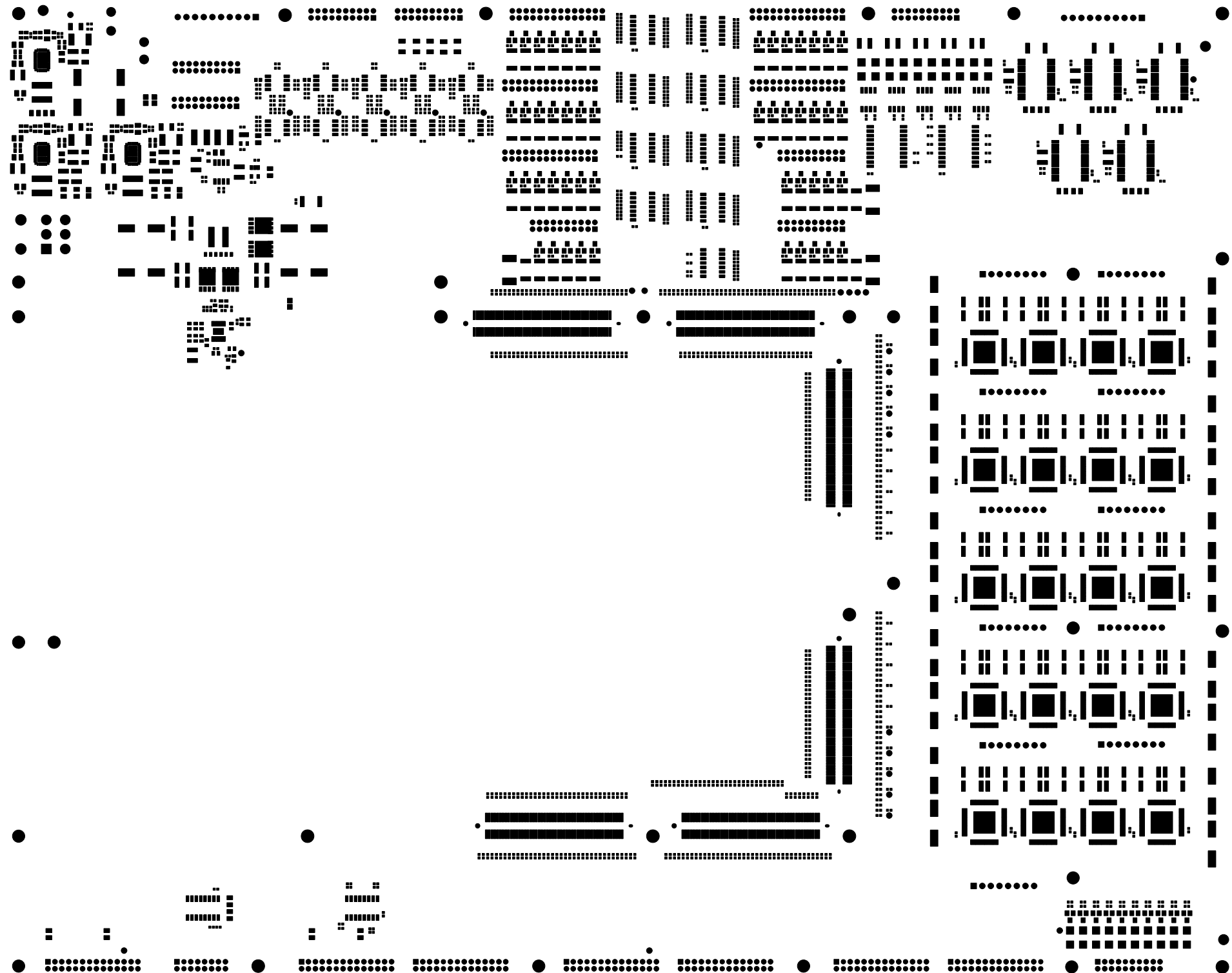


ECbETC2005-01



ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
LAYER 6			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:08/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

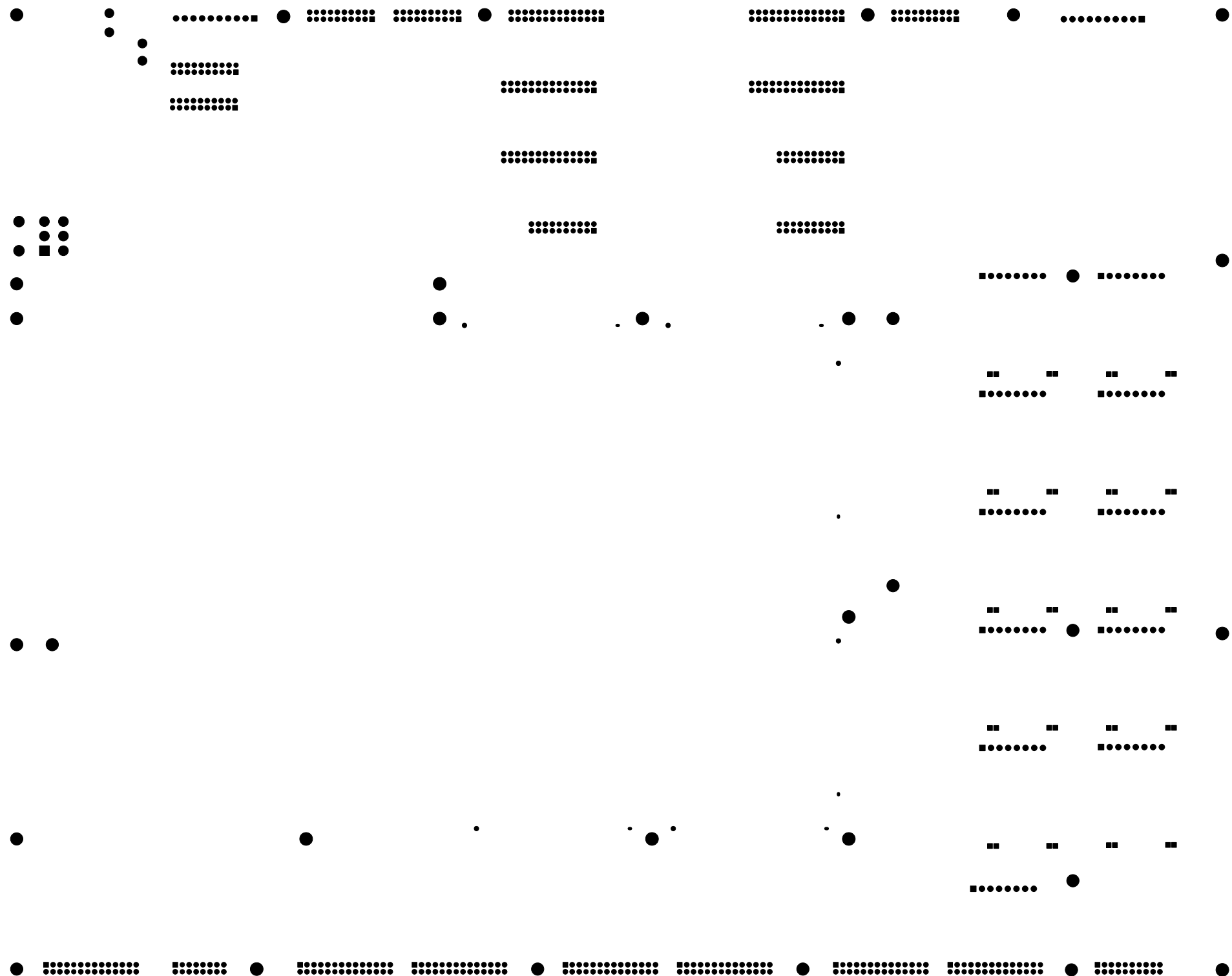




ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
SOLDER-RESIST LC			
FILE GERBER GENERATO CON OVERSIZE + 6 MILS			
Data:12/11/2020		DESIGN:PCBDes	CHECK:AG
		Pag:09/12	

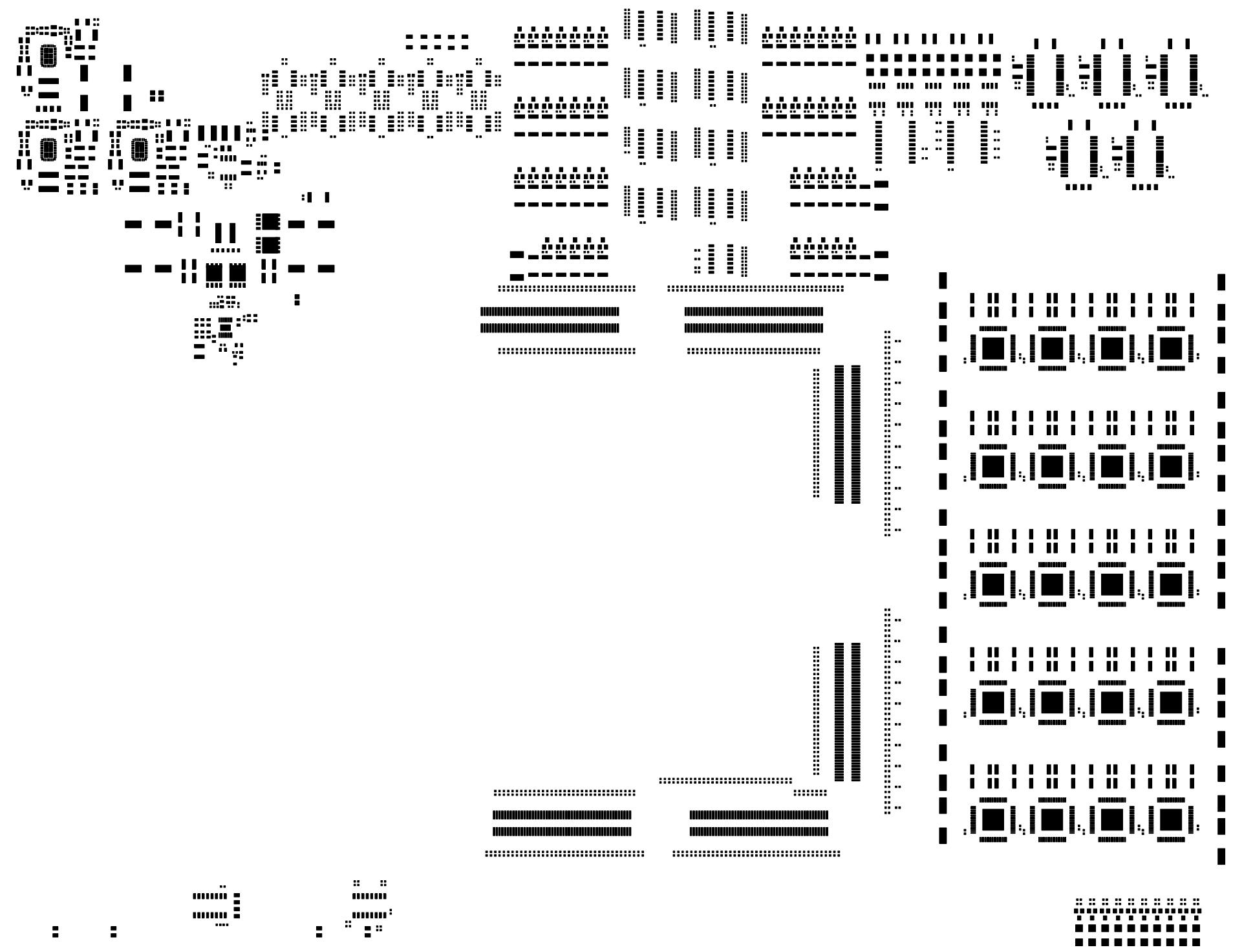
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<

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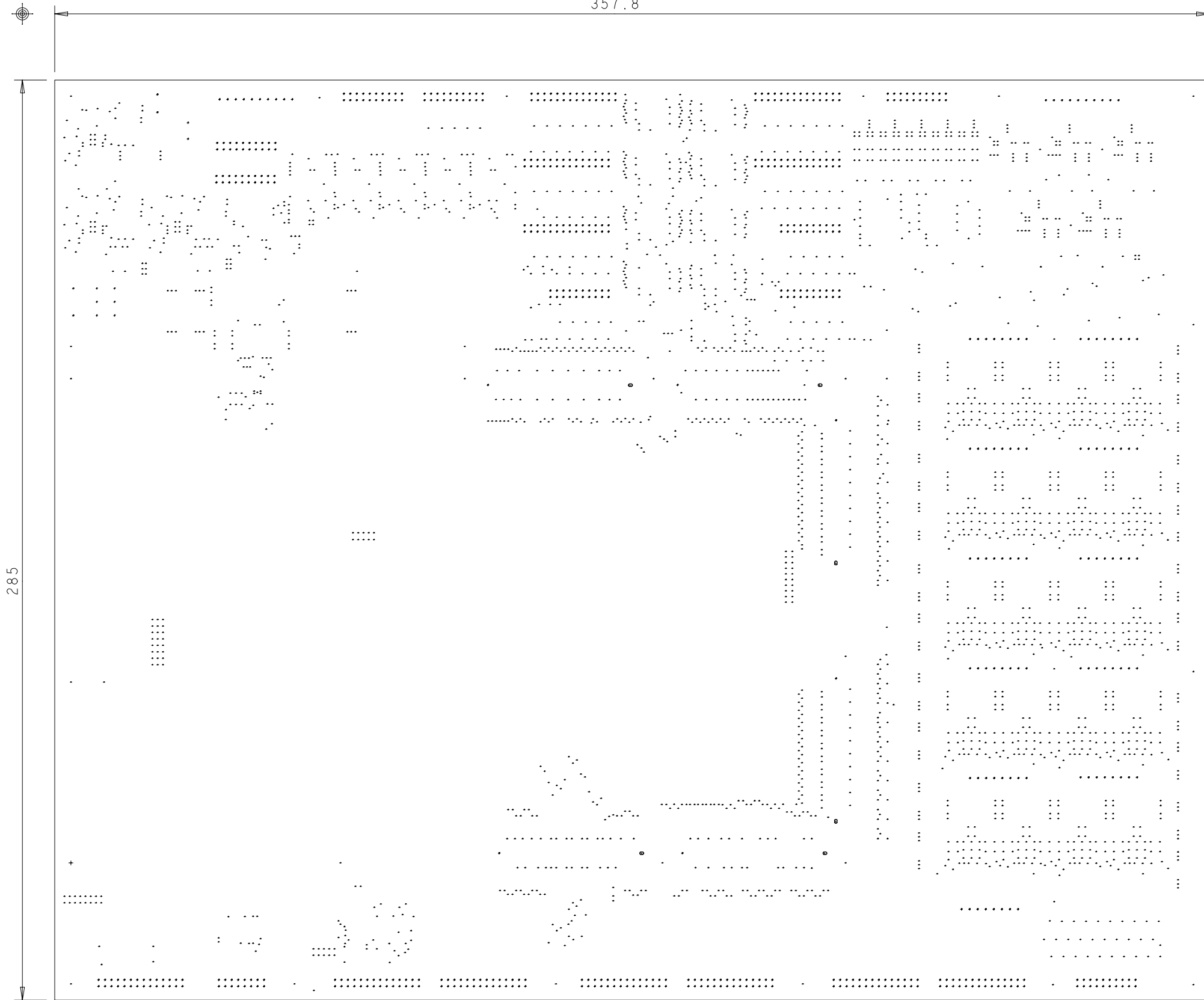


ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
SOLDER-RESIST LS			
FILE GERBER GENERATO CON OVERSIZE = 6 MILS			
Date:12/11/2020		DESIGN:PCBDes	CHECK:AG
		Pag:10/12	
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

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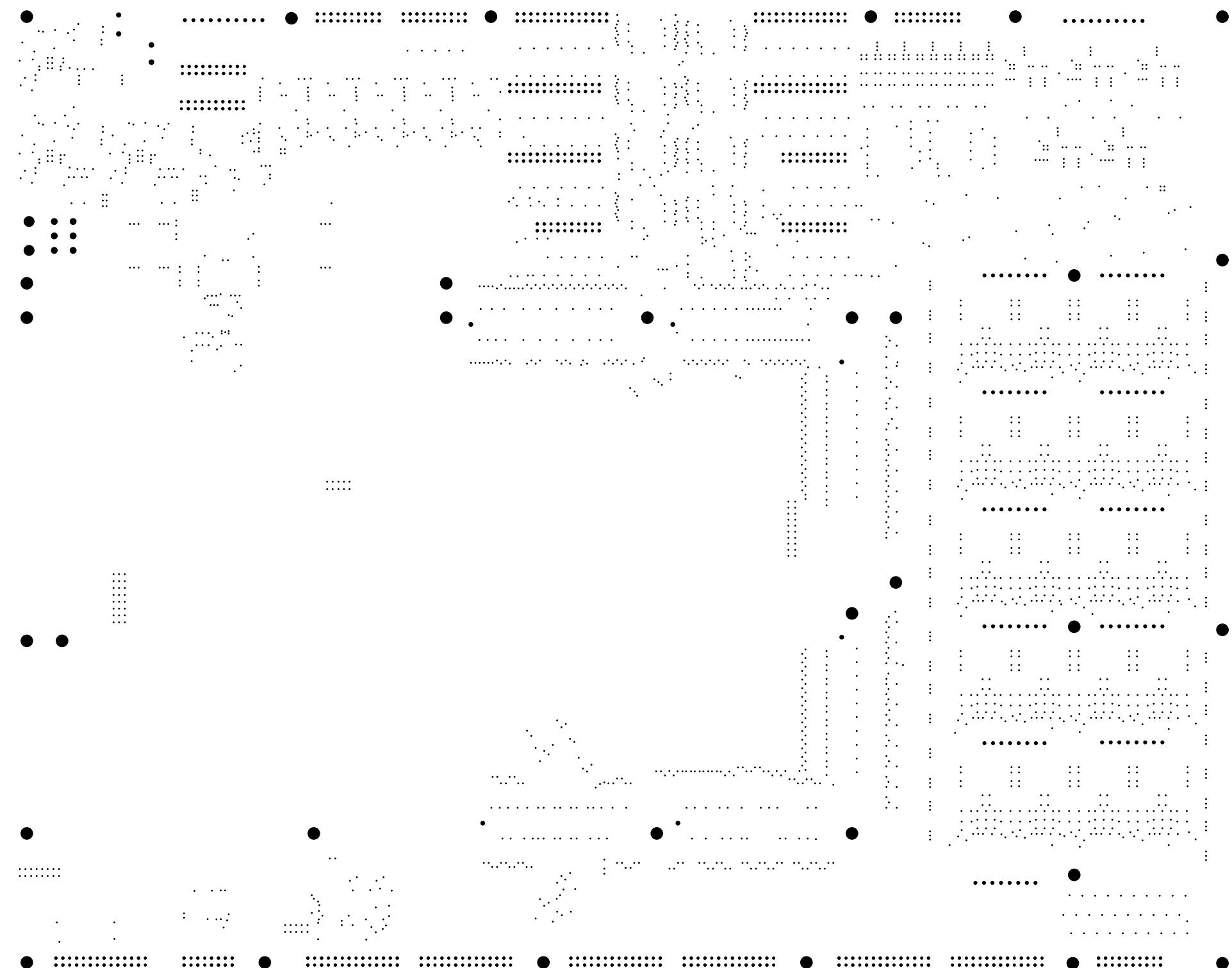


ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPELCS002		File: ECPELCS002-01.BRD	
SOLDER-PASTE LC			
FILE GERBER GENERATO CON OVERSIZE + 0 MILS			
Date:12/11/2020	DESIGN:PCBDes	CHECK:AG	Pag:11/12
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			



ROTOTYPE S.p.A.			
Board: RPB Rev.1			
PCB: ECPCLCS002		File: ECPCLCS002-01.BRD	
PIANO DI FORATURA			
QUOTE ESPRESSE IN mm, DIA.FORI IN mils (1 mil=0.0254 mm)			
Data:12/11/2020		DESIGN:PCBDes	CHECK:AG
		Pag:12/12	
>> STACKUP ALLEGATO ALLA DOCUMENTAZIONE DI PROGETTO <<			

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED_SIZE	PLATED	QTY
.	16.0	PLATED	2725
.	32.0	PLATED	532
.	39.0	PLATED	108
.	55.0	PLATED	2
.	59.0	PLATED	2
.	71.0	PLATED	6
.	47.0	NON-PLATED	6
.	118.0	NON-PLATED	2
.	138.0	NON-PLATED	32
•	47.0x32.0	NON-PLATED	2
•	47.0x32.0	NON-PLATED	4



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